Automotive Electronics Council
Component Technical Committee

Fourth European Automotive Electronics Reliability Workshop
(Bordeaux, France)

#	Title	Presenter	Company
SESSION 1: Passives, LEDs, WBG – Moderator Uwe Berger (Hella – Forvia)			
T1.1	Tantalum Polymer Capacitors Trends and Challenges - Software Defined Vehicles (SDV)	Cristina MotaCaetano	Yageo
T1.2	Need for speed? A Comparative Study of H2S-Corrosion Tests	Jennifer Rieder	amsOSRAM
T1.3	HVM "Golden Recipe" Methodology for SiC Substrate Qualification Across Suppliers	Jay Rathert; Michael Schmalz	KLA / Volkswagen
SESSION 2: Invited Papers – Moderator René Rongen (NXP Semiconductors)			
T2.1	SAFETY in cars	Franck Galtie	NXP Semiconductors
SESSION 3: Power Modules – Moderator Martin Geiger (Microchip)			
T3.1	Advanced Estimation of Remaining Useful Lifetime for Power Modules	Horst Lewitschnig	Infineon Technologies Austria AG
T3.2	Thermal Fatigue in Copper Wire Bonds under Power Cycling: Acceleration Model and Influence of Different Wire Types	Carlo Neva	STMicroelectronics
T3.3	New HAST and non-destructive evaluation methods for Power Modules	Etienne Wortham	Nexperia
SESSION 4: Extended / Severe Mission Profiles – Moderator Bassel Atala (STMicroelectronics)			
T4.1	Extended Lifetime Evaluation – An OEM Point of View	Stefan Simon	Audi
T4.2	Rethinking "Automotive": How to Specify Components for Tomorrow's Mobility	Francois Gouyou	Valeo
T4.3	Considerations and Challenges in the Use of AEC-Q Components for Space Missions	Gonzalo Fernandez; Anastasia Pesce	Alter Technology / ESA
SESSION 5: Zero Defects – Moderator Bassel Atala (STMicroelectronics)			
T5.1	Advancing Zero Defect Through Process-Oriented Reliability and Soft Error Risk Integration	Calvin Yang	SGS
T5.2	Technical cleanliness for electronic components	Uwe Berger	Hella (Forvia)
SESSION 6: Zero Defects / Memory – Moderator Martin Geiger (Microchip)			
T6.1	Outliers Detection for Zero Defect on Non-Normal and Highly Multivariate Data	Francois Bergeret; Francois Bourlon	Ippon Innovation / NXP Semiconductors
T6.2	Reliability Assessment of Single-Ended PCM in Automotive Microcontrollers Compliant with AEC-Q100 Standards	Fabio Dell'Orto	STMicroelectronics
SESSION 7: ESD – Moderator René Rongen (NXP Semiconductors)			
T7.1	New Contact-Based CDM Methods Needed to Align with ESD Roadmap	Greg O'Sullivan; Sumit Tayal	Micron

Thursday, October 30, 2025

Automotive Electronics Council
Component Technical Committee

Fourth European Automotive Electronics Reliability Workshop
(Bordeaux, France)

WORKSHOP SESSIONS			
#	**Title**	**Presenter**	**Company**
W1	Q102 / Optoelectronics	Uwe Berger	Hella (Forvia)
W2	Q200 / Passive Components	Alan Cooper	Yageo
W3	Q101 / Discrete Semiconductors	Andreas Pinkernelle	Nexperia
W4	Wide Band Gap Semiconductors (WBG)	Massimiliano Regardi	Nexperia
W5	Q007 / Board Level Reliability (BLR)	Romuald Roucou	STMicroelectronics
W6	Extended Mission Profiles (EMP)	Rene Rongen	NXP Semiconductors
W7A	Q004 / Zero Defects	Rene Rongen	NXP Semiconductors
W7B	Q006 / Cu-Wire	Rene Rongen	NXP Semiconductors
W8	Q100 IC & CDC Template	Bassel Atala	STMicroelectronics
W9	Q104 / Multi-Chip Modules (MCM)	Rene Rongen	NXP Semiconductors